

Introduction

X series is a professional deal with all kinds of advanced chip performance test, comprehensive and efficient semi-automatic wafer prober, integrates the electrical, light wave, microwave, etc, to 60 °C ~ 300 °C high temperature KuanQu and testing precision, can match various test application environment, at the same time super efficient well test run of the system speed > 70 mm/s, effectively improve testing efficiency by more than 40%, for all kinds of wafers and provide excellent reliability test device.



Application Direction

All kinds of devices and Wafer, etc., conduct characteristic analysis of I-V, C-V, optical signal, RF, 1/ F noise, RF test, high-power Wafer test, etc

Product Feature

- Super efficient and excellent test running speed >70mm/s, test efficiency increased by more than 40%
- Advanced 3 times patented optical microscopy system, high precision measurement and dynamic monitoring, more convenient operation of the point needle
- -60°C~300°C ultra-high temperature wide area
- Software automation test, precise calibration of mechanical accuracy
- Integrated control system, instrument fast and convenient access test
- Excellent test accuracy, operating efficiency and system stability
- Support automatic expansion and upgrade

Specification

Model	SX-6	SX-8	SX-12	
Dimension (W*L*H)	1000mm * 1400mm * 1400mm	1100mm * 1500mm * 1400mm	1200mm * 1600mm * 1400mm	
Weight(about)	1000KG	1150KG	1350KG	
Electricity Demand	AC220V, 50~60Hz			
CDA demand	0.4~0.8Mpa			
Chuck	Size	6"	8"	12"
	X-Y Travel range	200mm * 300mm	250mm * 400mm	350mm * 500mm
	X-Y Resolution	0.1µm		
	X-Y Repeatability	≤±1µm		
	X-Y Move speed	≥70mm/sec		
	Z Travel range	20mm		
	Z Resolution	0.1µm		
	Z Repeatability	≤±1µm		
	Z Move speed	≥20mm/sec		
	Theta Travel range	±10°	Theta resolution	0.0001°
Sample Fixed mode	Vacuum adsorption , Independent control			
Sample Exchange	Chuck quickly roll out for wafer fast exchange.			
Structure	Triaxial ultra-low noise design,Gold plating, Chuck surface is electrical floating			
Platen	Specifications O shape platen, 12 micropositioners available (When the octagon box is not installed)			

Model	SX-6	SX-8	SX-12
Microscope X-Y-Z	X-Y Travel range	2" * 2"	
	X-Y Resolution	0.1µm	
	X-Y Repeatability	±2µm	
	X-Y Move speed	≥10mm/sec	
	Z Travel range	5"	
	Z Resolution	0.1µm	
	Z Repeatability	≤ ±1µm	
Microscope	Z Move speed	≥10mm/sec	
	Variable magnification microscope	Zoom:15: 1,Three gears and could display low(0.6X) and high(2.5X or 9X) magnification in the same time	
Microscope	Camera	Double cameras (200W or 500W Industrial digital camera)	
	Mechanical resolution	10µm / 2µm / 0.7µm	
Micropositioner Specification	X-Y-Z Move range	13mm-13mm-13mm	
	Current leakage	10pA / 100fA / 10fA	
	Connector type	Banana plug adapter/Coaxial /Three-axis/ SMA /SHV etc.	
	Base	Magnetic/vacuum adsorption base	
Temperature specification	Temperature range	- 60°C-200°C (Standard), other Temperature range upon request	
	Temperature stability	±0.1°C	
	Temperature resolution	0.01°C	
	Heating time(12"chuck)	- 60°C to +25°C ≤ 10min	
		+25°C to +200°C ≤10 min	
	Cooling time(12"chuck)	+ 200°C to +25°C ≤ 12min	
		+ 25°C to -60°C ≤ 25min	
	Noise	<60dB	
Heating method	Low Voltage DC(LVDC)/PID control		
Refrigeration method	Refrigeration compressor		
Anti-Vibration	Anti-Vibration method	Air film anti-vibration system, Ensure nonvisible vibration in the screen when the microscope zooming in at 2000X	
	Vibration suppression	In the process of chuck movement, it can be extremely fast to ensure the stability of the chuck ≤1S, Improve the test efficiency.	
system mask	EMI shielding	> 20 dB (typical) @ 1 kHz to 20GHz	
	Light attenuation	≥ 120 dB	
	Spectral noise floor	≤ -150 dBVrms/rHz	
	System AC noise	≤15 mVp-p (≤ 1 GHz)	
Software function			
Automatic wafer alignment		Automatic wafer height measurement and compensation	
Automatic Die size measurement and auto mapping		Support Z, N shape test	
Wafer map edit arbitrary		One touch automatic RF calibrate and probe tips cleaning	
Demarcate difference data with Ink mark		Separation of OS and application software, can be upgraded independently.	
Real-time test results display		Robust data storage and processing capabilities	
Easy data management of the instrument input/output		Automatic data and curves storage and remote access	
The test results can be divided into different bin values		Communication interface: R232/485/TCP/IP/GPIB	
Multi tester fast integration , support both single Die testing and continuous testing			